

PATENT ABSTRACTS OF JAPAN

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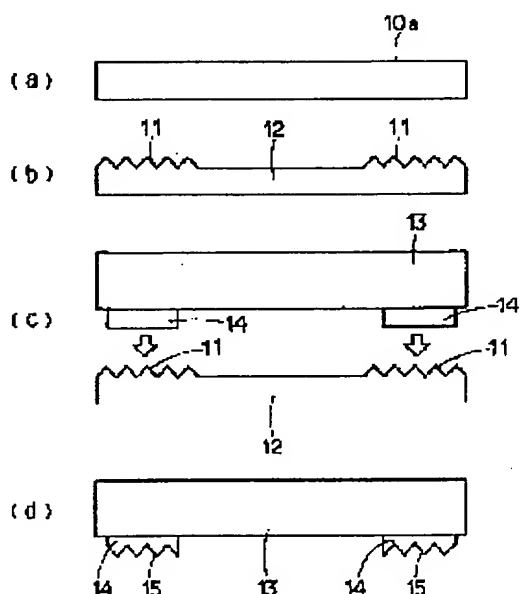
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 (22)Date of filing : 03.07.1991 (72)Inventor : TANAKA AKIHIRO

(54) BUMP FORMING METHOD FOR SEMICONDUCTOR ELEMENT

(57)Abstract:

PURPOSE: To obtain recesses and protrusions uniformly on the bump section of a semiconductor element for a face-down mounting.

CONSTITUTION: A mold 12, to be used for a bump formation, is manufactured by forming recesses and protrusions in uniform depth on a plate material 10a to be used for a mold, and on the other hand, after formation of flat bumps 14 on the electrode part of a semiconductor element 13, the bump part 14 of the semiconductor element 13 is stamped on the recess and protrusion part 11 of the mold 12 to be used for a bump, and grooves 15, having recesses and protrusions in uniform depth, is formed.



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